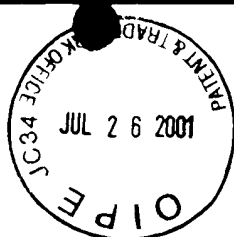


S/N 09/854,539



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Steven Towle	Examiner:	Unknown
Serial No.:	09/854,539	Group Art Unit:	3729
Filed:	May 14, 2001	Docket:	884.415US1
Title:	POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT PACKAGING		

COMMUNICATION RE: INCORRECT FILING RECEIPT

Commissioner for Patents
Washington, D.C. 20231

Applicants hereby request correction of the Filing Receipt with respect to the above-identified patent application. In the Filing Receipt received July 17, 2001, (copy enclosed), the Title is incorrect. The Filing Receipt reads: *Polymeric Encapsulation Material with Fibrous Filler for use in **Microelectric** Circuit Packaging*. The Filing receipt should read: *Polymeric Encapsulation Material with Fibrous Filler for use in **Microelectronic** Circuit Packaging*. This is evidenced by the first page of the application (copy enclosed).

Applicant would appreciate the above-identified printing error be corrected and that a new "corrected" filing receipt be sent to Applicant's representatives at the address given below.

Respectfully submitted,

STEVEN TOWLE

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date July 24, 2001 By Ann M. McCrackin

Ann M. McCrackin
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I hereby certify that this correspondence is being
deposited with the United States Postal Service as first
class mail in an envelope addressed to Assistant
Commissioner of Patents, Washington, D.C. 20231,
on July 24, 2001
Date of Deposit

ANN MCCRACKIN
Ann M. McCrackin



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/854,539	05/14/2001	3728	782	884.415US1	6	24	3

CONFIRMATION NO. 8328

FILING RECEIPT



OC000000062R2394

Schwegman, Lunberg, Woessner & Kluth, P.A.
P.O. Box 2938
Minneapolis, MN 55402

Date Mailed: 07/11/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Steven Towle, Phoenix, AZ.

Assignment For Published Patent Application

Intel Corporation;

14 MAY 2002 CONV. EXP.

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 07/10/2001

Projected Publication Date: 11/14/2002

Schwegman, Lunberg
Woessner & Kluth, P.A.

Non-Publication Request: No

JUL 17 2001

Early Publication Request: No

RECEIVED

Title

Polymeric encapsulation material with fibrous filler for use in microelectric circuit packaging

Preliminary Class

029

UNITED STATES PATENT APPLICATION

**POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN
MICROELECTRONIC CIRCUIT PACKAGING**

INVENTOR

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ATTORNEY DOCKET SLWK 884.415US1US1

Client Ref. No. P10931



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Steven Towle

Title: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN
MICROELECTRONIC CIRCUIT PACKAGING

Docket No.: 884.415US1

Filed: May 14, 2001

Examiner: Unknown

Serial No.: 09/854.539

Due Date: N/A

Group Art Unit: 3729

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the attached:

- ☒ Communication Re: Incorrect Filing Receipt (1 pg.)
- ☒ Copy of Filing Receipt (1 pg.)
- ☒ A return postcard.
- ☒ Copy of the First Page of the Application (1 pg.)

No Additional fee is required.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Ann M. McCrackin
Name: Ann M. McCrackin
Reg. No. 42,858
AMM:CMG:clh

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 24 day of July, 2001.

ANN MCCRACKIN
Name

Ann M. McCrackin
Signature